

N-Ch MOSFET

#### **General Description**

The WSK150N10 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSK150N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

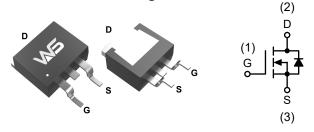
### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	3.7mΩ	150A

### Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

### **TO-263-2L Pin Configuration**



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±25	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	150	А
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	90	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°C	600	А
EAS	Avalanche Energy, Single pulse	545	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse	60	A
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	225	W
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C
TJ	Operating Junction Temperature Range	-55 to 150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W	
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		0.55	°C/W	



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### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V	
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.096		V/℃	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =80A		3.7	4.2	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage		2.5	3.0	4.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	VGS-VDS, ID -2500A		-5.5		mV/℃	
la sa	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			1	uA	
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}55^\circ\!\mathrm{C}$			5		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm20V$ , $V_{DS}$ = $0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =50A		120		S	
R <sub>g</sub>	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f=1MHz		0.7	1.5	Ω	
Qg	Total Gate Charge (10V)			80			
Q <sub>gs</sub>	Gate-Source Charge	$V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}10\text{V}$ , $I_{\text{D}}\text{=}80\text{A}$		33		nC	
Q <sub>gd</sub>	Gate-Drain Charge			18			
T <sub>d(on)</sub>	Turn-On Delay Time			28			
Tr	Rise Time	$V_{DD}$ =50V , $V_{GS}$ =10V ,		55		20	
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =5Ω, I <sub>D</sub> =80A		98		ns	
T <sub>f</sub>	Fall Time			24			
C <sub>iss</sub>	Input Capacitance			4120			
Coss	Output Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		1250		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			65			

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V$ , Force Current			80	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =50A , TJ=25℃		0.8	1.3	V
t <sub>rr</sub>	Reverse Recovery Time			85		nS
Qrr	Reverse Recovery Charge	IF=50A,dI/dt=100A/µs,Tյ=25℃		200		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec. 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2% 3. The EAS data shows Max. rating . The test condition is V<sub>DS</sub>=80V,V<sub>GS</sub>=10V,L=0.1mH,

5. The Min. value is 100% EAS tested guarantee.

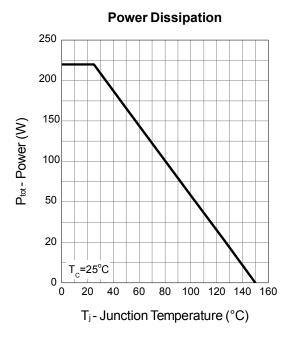
6.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

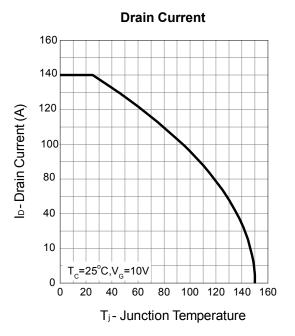
<sup>4.</sup> The power dissipation is limited by 150  $^\circ\!\mathrm{C}$  junction temperature



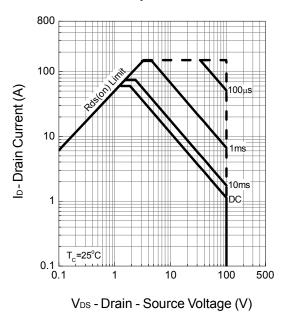
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### **Typical Operating Characteristics**

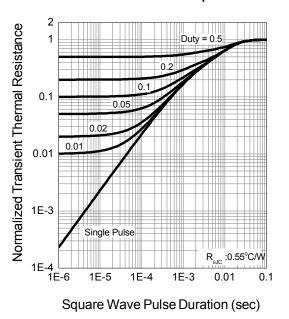




Safe Operation Area



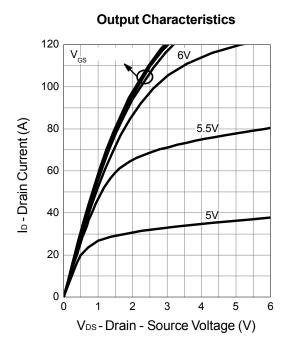
**Thermal Transient Impedance** 





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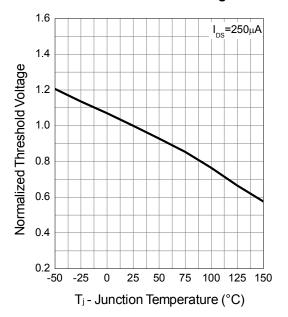
### **Typical Operating Characteristics**



**Drain-Source On Resistance** 

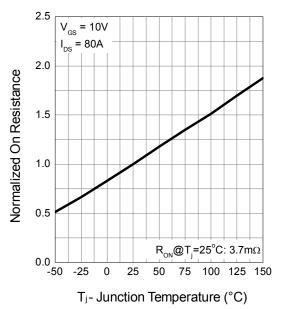
**Gate-Source On Resistance** 40 I<sub>DS</sub>=80A 35  $R_{DS(ON)}$  - On - Resistance (m $\Omega$ ) 30 25 20 15 10 5 6 7 8 9 10 4 VGS - Gate - Source Voltage (V)

Gate Threshold Voltage





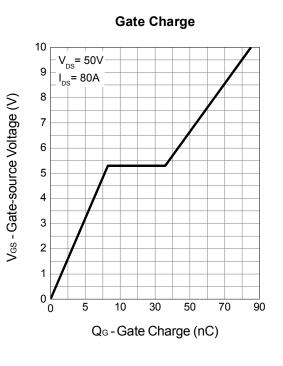
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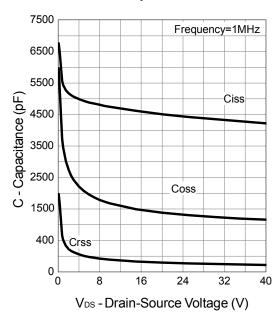
### Drain-Source On Resistance

 $(V) = 10 + T_{j} = 150^{\circ}C + T_{j} = 25^{\circ}C + T_{j} = 25^{\circ}C$ 

# Source-Drain Diode Forward



### Capacitance



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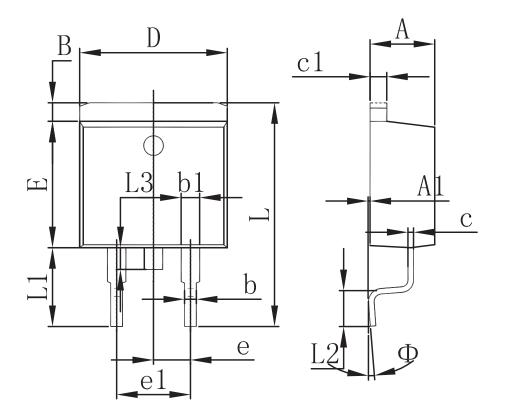
## WSK150N10

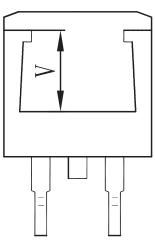
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### Packaging information





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.470	4.670	0.176	0.184	
A1	0.000	0.150	0.000	0.006	
В	1.120	1.420	0.044	0.056	
b	0.710	0.910	0.028	0.036	
b1	1.170	1.370	0.046	0.054	
С	0.310	0.530	0.012	0.021	
c1	1.170	1.370	0.046	0.054	
D	10.010	10.310	0.394	0.406	
E	8.500	8.900	0.335	0.350	
е	2.540 TYP.		0.100 TYP.		
e1	4.980	5.180	0.196	0.204	
L	14.940	15.500	0.588	0.610	
L1	4.950	5.450	0.195	0.215	
L2	2.340	2.740	0.092	0.108	
L3	1.300	1.700	0.051	0.067	
Φ	0°	8°	0°	8°	
V	5.600 REF.		0.220REF.		



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